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(57) **ABSTRACT**

A substrate processing method includes: performing a both-surface cleaning processing in which a first cleaning body, which ejects the fluid to the one surface or is brought into contact with the one surface, and subsequently moves both the first cleaning body and a second cleaning body, which is in contact with the remaining surface of the upper surface and the lower surface of the substrate and rotated around a first vertical axis, horizontally in synchronization with each other toward an outer peripheral portion of the substrate, and performing a side end cleaning processing in which a third cleaning body is rotated around a second vertical axis and brought into contact with the side end of the substrate to clean the side end of the substrate while simultaneously performing the both-surface cleaning processing.

